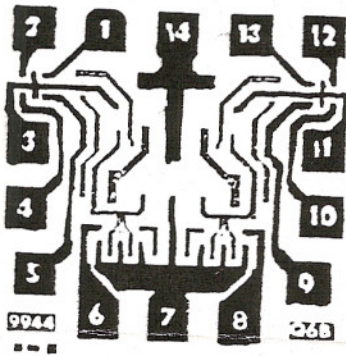




Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



PAD NO.	PAD FUNCTION
1	Input A
2	Input A
3	Extender A
4	Input A
5	Input A
6	Output A
7	Gnd
8	Output B
9	Input B
10	Input B
11	Extender B
12	Input B
13	Input B
14	V _{CC}

Topside Metal:
Backside:
Backside Potential:
Mask Ref:
Bond Pads (Mils):

APPROVED BY:
MFG: National

DIE SIZE (Mils): .036X.010+/-0.003
THICKNESS:

DATE: 3/20/00
P/N: DS55115

DG 10.1.2
 Rev A 3-4-99